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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Gérard-Marie Martin et al.

Group Art Unit: Unassigned

International Application No.: PCT/FR00/02098

International Filing Date: July 21, 2000

Examiner: Unassigned

Serial No.: Unassigned

Filed: Herewith

For: ELECTRONIC ASSEMBLY
COMPRISING A SOLE PLATE
FORMING A HEAT SINK

Atty. Docket: LLBR:0003/YOD
(BR 3085)

Assistant Commissioner
For Patents
Washington, D.C. 20231

"EXPRESS MAIL" MAILING LABEL	
NUMBER:	EL652335329US
DATE OF DEPOSIT:	March 23, 2001
<p>Pursuant to 37 C.F.R. § 1.10, I hereby certify that I am personally depositing this paper or fee with the U.S. Postal Service, "Express Mail Post Office to Addressee" service on the date indicated above in a sealed envelope (a) having the above-numbered Express Mail label and sufficient postage affixed, and (b) addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.</p>	
March 23, 2001	<i>Lynda Howell</i>
Date	Lynda Howell

Dear Sir:

PRELIMINARY AMENDMENT

Prior to calculation of the fees for and examination of the above-referenced National Phase filing, please amend the subject application as follows:

IN THE CLAIMS

Please cancel claims ~~1-8~~ without prejudice.

Please add the following new claims:

9. (New) An assembly supported on a base forming a radiator or capable of being mounted on such a base, comprising a printed circuit card which has in its thickness a plurality of

holes intended to transfer heat between one face of the said printed circuit card, which supports one or more electronic components each enclosed by a box, and the base forming a radiator, having a plurality of pads which are made of a thermally conductive material and pass through the printed circuit card over substantially its whole thickness while being housed by the holes therein, in order to transfer heat between one face of the printed circuit card, which supports one or more components, and the base, the pads are integral with a plate, referred to as the sole plate, which supports them, wherein the sole plate is interposed between the printed circuit card and the base.

10. (New) The assembly according to claim 9, wherein the sole plate is made of the same material as the bottom of the box of components or of a material with similar coefficient of expansion and/or electrical conductivity.

11. (New) The assembly according to claim 9, comprising a ductile thermal joint through which it is in contact with the base.

12. (New) The assembly according to claim 10, wherein pads are directly supported by the box of electronic components and are in contact with the base through a ductile joint.

13. (New) The assembly according to claim 9, wherein the sole plate has complementary means capable of mechanically holding it to the card.

14. (New) The assembly according to claim 13, wherein the complementary holding means are spikes which are supported by the sole plate and are force-fitted into holes in the printed circuit card.

15. (New) The assembly according to claim 9, wherein the sole plate and the pads are soldered to the printed circuit card in order to spread the thermal dissipation.

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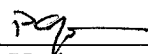
16. (New) The assembly according to claim 9, wherein the sole plate and the pads are soldered to the printed circuit card in order to spread the thermal dissipation and wherein the sole plate has through-holes for discharging the residual air possibly trapped in the solder.

REMARKS

If the Examiner believes that a telephonic interview will help speed this application toward issuance, Applicant invites the Examiner to contact the undersigned at (281) 970-4545.

Respectfully submitted,

Date: March 23, 2000



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